ABSTRACT

HEATSINK AND PACKAGE STRUCTURE FOR WIREBOND CHIP REWORK AND REPLACEMENT

A direct chip attach to heatsink structure is shown and described which implements rework when the chip (10) must be removed and replaced. A laminated heatsink (20) includes a metal heatsink (22) with a foil layer (24) adhered to the chip attachment surface with the assembly secured to a carrier at a cutout opening therein that defines the chip attach site. The adhesive (26), either a dry film adhesive or a pressure sensitive adhesive, secures foil layer to heatsink and provides the interface of separation when a chip must be removed and replaced. By peeling the foil away from the heatsink, the foil, chip and non-reworkable die attach adhesive are removed as a unit, leaving no chip attach adhesive residue at the attachment site to be scraped or abraded away.

Fig. 1

This Sheet Has Been Replaced

